

T10 Thermally Conductive Compound

Gray, thixotropic, non-curing thermally conductive compound

Features & Benefits

- One part material – no cure required
- Solvent free formulation – provides material stability
- Easy application – Screen printable
- Thixotropic – low slump
- High thermal conductivity
- Achieves thin Bond Line Thickness (BLT)
- Low thermal resistance



Composition

- Thermally conductive fillers
- Siloxane polymer matrix

Applications

T10 Thermally Conductive Compound is designed to provide efficient thermal transfer for the cooling of modules, including computer MPUs and power modules.

Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
Color		Gray
One Part Material		Non-curing
Viscosity	cP	140,000
Viscosity	Pa-s	140
Specific Gravity		2.7
Volatile Content, 48 hours at 125°C	%	0.18
Thermal Conductivity	W/mK	13.9
Thermal Resistance at 25 N/cm ²	°C-cm ² /W	0.03
Bond Line Thickness at 25 N/cm ²	mm	0.02
	inch	0.0008

Description

Thermally conductive compounds are grease like materials that are highly loaded with thermally conductive fillers in a silicone matrix. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive heat sink seal to improve heat transfer from an electrical device or PCB system assembly to a heat sink or chassis, thereby increasing the overall efficiency of the device. PCB system assemblies are continually designed to deliver higher performance.